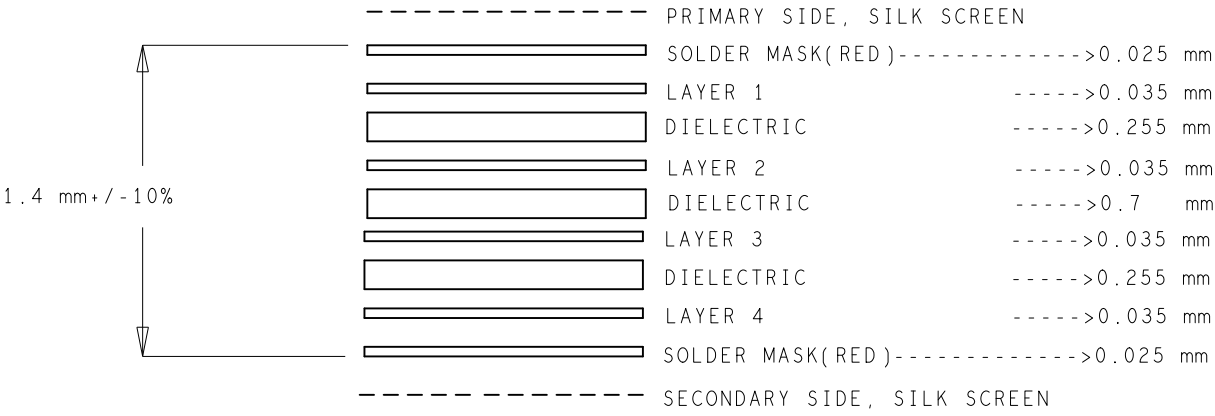


4-LAYER STACK BUILD

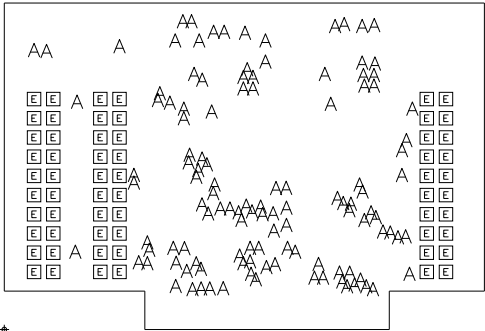


SECTION A-A

NO SCALE

GENERAL NOTES-- UNLESS OTHERWISE SPECIFIED:

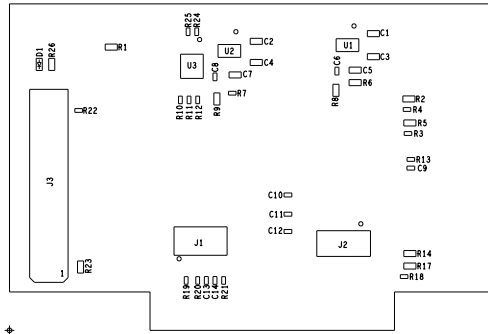
1. FABRICATE PER IPC-6012A CLASS 2
2. SURFACE FINISH : ENIG
3. MATERIAL; FR4
5. COPPER WT: 1 Oz
6. SOLDER MASK COLOUR : RED



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
A	12.0	+0.0/-12.0	PLATED	120
E	38.0	+3.0/-3.0	PLATED	60

TEXAS INSTRUMENTS			
NAME: CAMBOOST			
DATE :	28 APRIL 2014	REV	4.0
LAYER: FAB DRAWING			

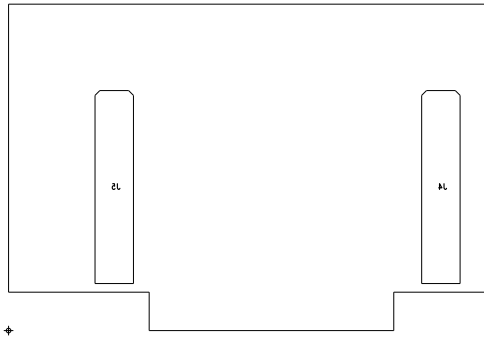
ALL DIMENSION ARE IN MILS UNLESS OTHERWISE SPECIFIED	TEXAS INSTRUMENTS						
DRAWN BY :	FABRICATION DRAWING CAMBOOST						
CHECKED BY :							
APPROVED BY :							
	SCALE	NONE	REV	4.0	SIZE	B	



TEXAS INSTRUMENTS			
NAME : CAMBOOST			
DATE :	28 APRIL 2014	REV	4.0
LAYER: ASSEMBLY TOP			

ALL DIMENSION ARE IN MILS UNLESS OTHERWISE SPECIFIED	TEXAS INSTRUMENTS				
DRAWN BY:	ASSEMBLY: CC31XX_CAMERA_ADAPTER_BP				
CHECKED BY:					
APPROVED BY:					
SCALE	NONE	REV	2.0	SIZE	B

VIEWED FROM TOP SIDE



TEXAS INSTRUMENTS		
NAME : CAMBOOST		
DATE :	28 APRIL 2014	REV 4.0
LAYER: ASSEMBLY BOTTOM		

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